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Harold C. Moore

Name of person mailing Document or Fee

Signature

June 1, 2005

Date of Signature

Re:	Application of:	Tilke et al.
	Serial No.:	10/780,276
	Filed:	February 17, 2004
	For:	Semiconductor Structure with Increased Breakdown Voltage and Method for Producing the Semiconductor Structure
	Group Art Unit:	2811
	Confirmation No.:	7063
	Examiner:	Thien F. Tran
	Our Docket No.:	1890-0061

**SUBMISSION OF PRIORITY DOCUMENT**

Please find for filing in connection with the above patent application a certified copy of the priority document, Certified Copy of German Application Number 103 06 597.0.

DOCKETED  
6/10/05 *lan*

Please charge any fee deficiency or credit any overpayment to Deposit Account  
No. 13-0014.

Respectfully submitted,

A handwritten signature in black ink, appearing to read 'H. C. Moore', written over a horizontal line.

June 1, 2005

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Enclosures